



Field of Application
SMT-Stencil cleaning within automatic
cleaning equipment

Customer benefits
Concentrate to dilute with DI-water. Efficient removal of
solder paste and SMT-adhesive from especially μ BGA
and Fine-pitch stencils grants repeatable and stable
cleaning process which helps to achieve high-quality
printing results. The waterbased formulation combines
high flashpoint and work safety level and helps to
eliminate flammable solvents from within the
production area

Please consider approvals of equipment manufacturer!

Technical Data

Appearance / Consistency: Colorless to slightly yellow, clear

Application: 1 part concentrate : 4 parts DI water

Density at 20°C: 0,923 +/- 0,005 g/cm³

pH-value Alkaline

Boiling point / boiling range: >100°C

System: Waterbased (ready-mix)

Flashpoint: None (ready-mix)

Operations temperature: Room temperature

Reliable cleaning results with: Leaded, lead-free, no-clean solder pastes
SMT-adhesives

Shelf life (month) 36

Storage conditions Ideal in original packaging at 10-25°C

Transportation: Non-DG

Packaging: 5 L blue plastic can
20 L green plastic can

Application notes:

The waterbased, slightly alkaline cleaning concentrate is blended 1 part to 4 parts DI-water (equals ready diluted **Etimol SW 26 RAA**) to efficiently remove leaded, lead-free, no-clean solder pastes and SMT-adhesives from especially μ -BGA and Fine-pitch SMT-stencils within automatic cleaing equipment. The innovative blend shows excellent dissolving properties that grant stable and high quality cleaning results and shows excellent rinsability DI-water.

The cleaning media is used straight at room temperature and put within the cleaning tank of the automatic equipment.

Consider approvals of equipment manufacturer!

Consider compatibility of SMT-stencil adhesive!